

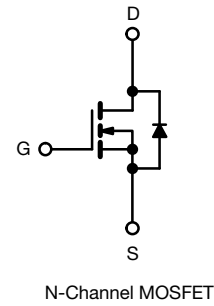
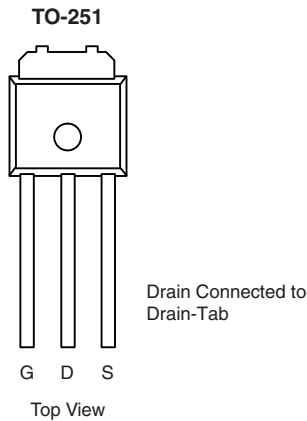
FQU8N25TU-VB Datasheet

N-Channel 250 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	250	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.176
Q_g max. (nC)	68	
Q_{gs} (nC)	11	
Q_{gd} (nC)	35	
Configuration	Single	

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	250	V
Gate-Source Voltage			V _{GS}	± 20	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	I _D	17	A
		T _C = 100 °C		11	
Pulsed Drain Current ^a			I _{DM}	56	
Linear Derating Factor				1.0	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	550	mJ
Repetitive Avalanche Current ^a			I _{AR}	17	A
Repetitive Avalanche Energy ^a			E _{AR}	13	mJ
Maximum Power Dissipation	T _C = 25 °C		P _D	125	W
Peak Diode Recovery dV/dt ^c			dV/dt	4.8	V/ns
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Soldering Recommendations (Peak temperature) ^d		for 10 s		300	
Mounting Torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

Notes

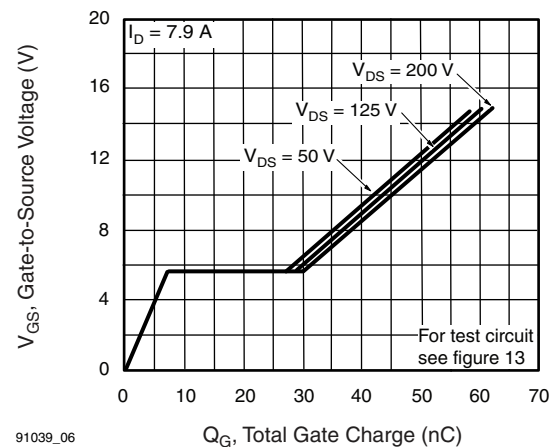
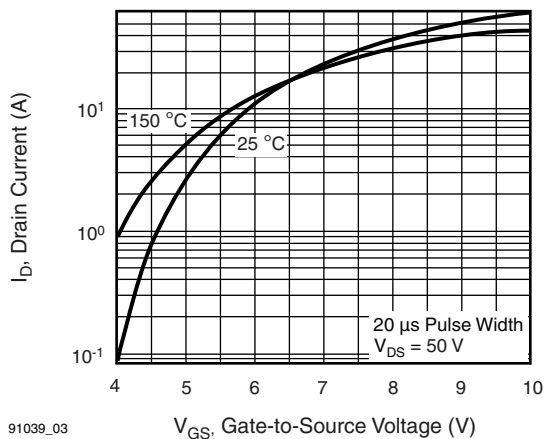
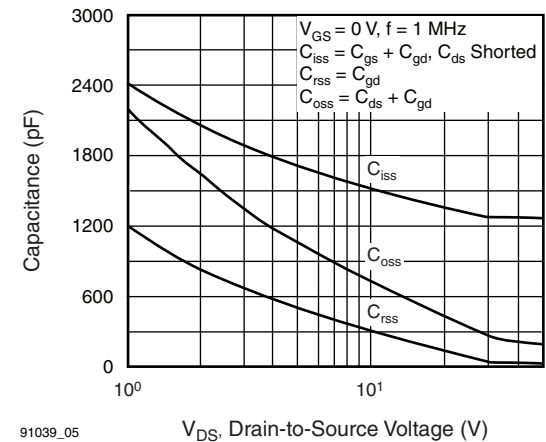
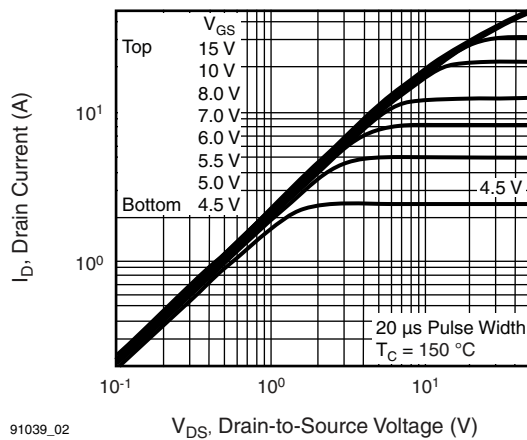
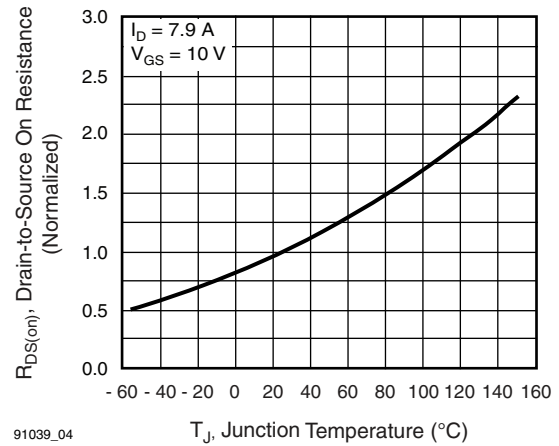
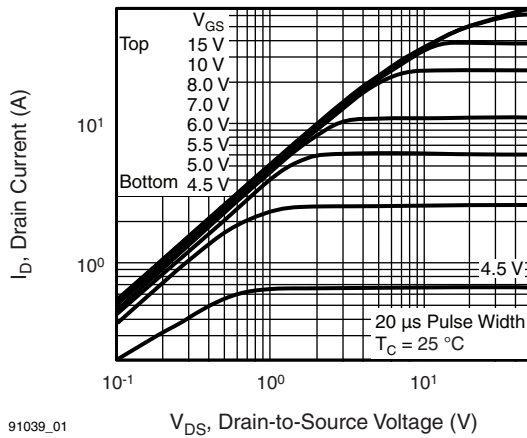
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. $V_{DD} = 50\text{ V}$, starting $T_J = 25\text{ }^\circ\text{C}$, $L = 4.5\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 14\text{ A}$ (see fig. 12).
 c. $I_{SD} \leq 14\text{ A}$, $dI/dt \leq 150\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
 d. 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.50	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.0	

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		250	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.34	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V		-	-	25	μA
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8.4 A ^b	-	0.176	-	Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 8.4 A ^b		6.7	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	1300	-	pF
Output Capacitance	C _{oss}			-	330	-	
Reverse Transfer Capacitance	C _{rss}			-	85	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 7.9 A, V _{DS} = 200 V, see fig. 6 and 13 ^b	-	-	68	nC
Gate-Source Charge	Q _{gs}			-	-	11	
Gate-Drain Charge	Q _{gd}			-	-	35	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 125 V, I _D = 7.9 A, R _g = 9.1 Ω, R _D = 8.7 Ω, see fig. 10 ^b		-	11	-	ns
Rise Time	t _r			-	24	-	
Turn-Off Delay Time	t _{d(off)}			-	53	-	
Fall Time	t _f			-	49	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Gate Input Resistance	R _g	f = 1 MHz, open drain		0.3	-	1.2	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	14	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	56	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 14 A, V _{GS} = 0 V ^b		-	-	1.8	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 7.9 A, dI/dt = 100 A/μs ^b		-	250	500	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	2.3	4.6	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


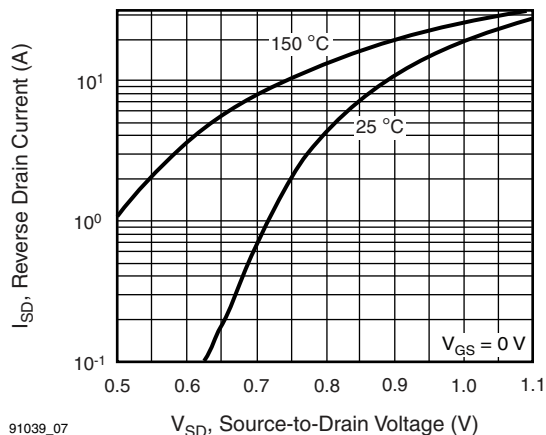


Fig. 7 - Typical Source-Drain Diode Forward Voltage

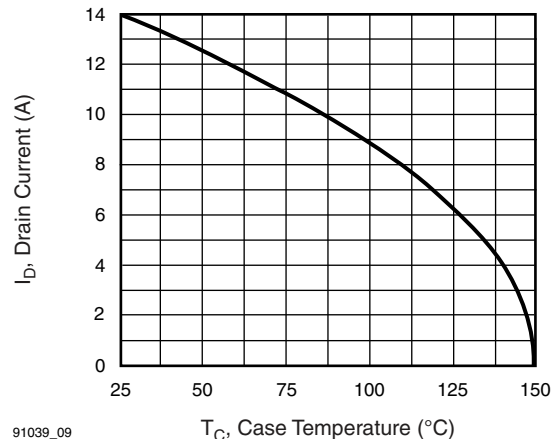


Fig. 9 - Maximum Drain Current vs. Case Temperature

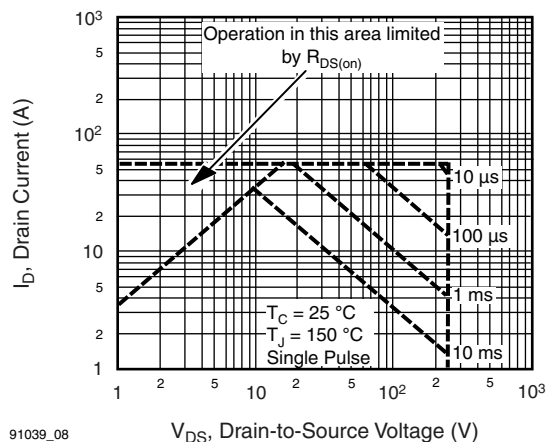


Fig. 8 - Maximum Safe Operating Area

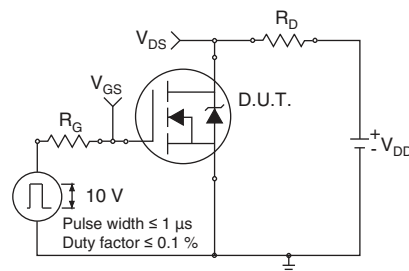


Fig. 10a - Switching Time Test Circuit

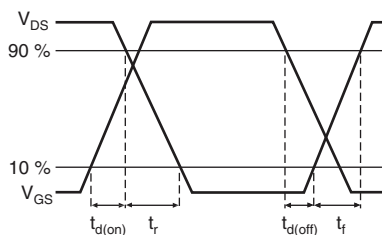


Fig. 10b - Switching Time Waveforms

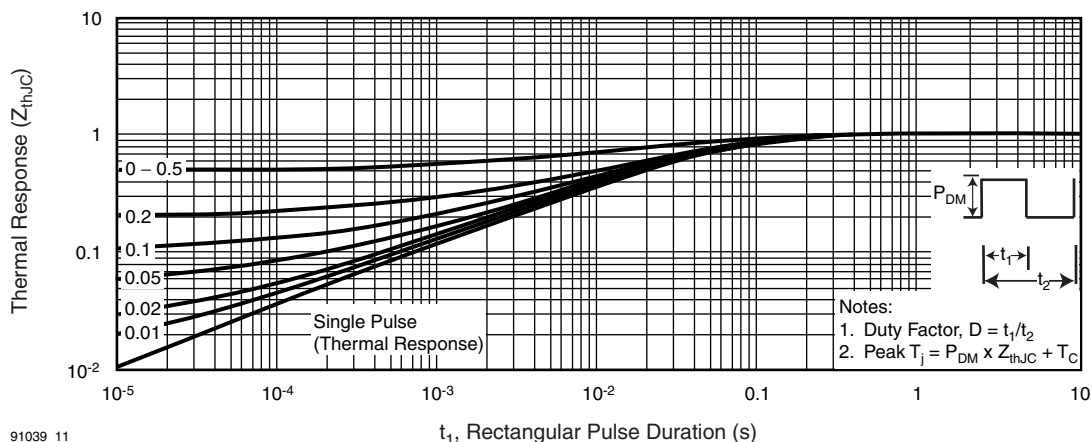


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

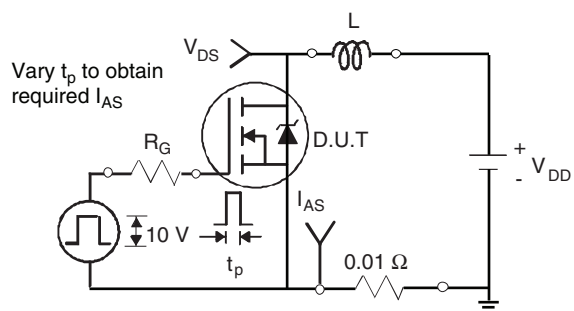


Fig. 12a - Unclamped Inductive Test Circuit

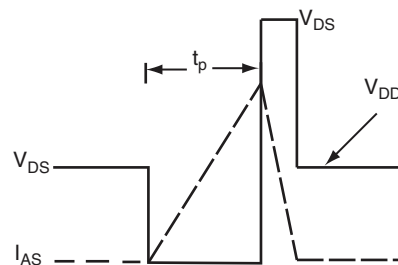


Fig. 12b - Unclamped Inductive Waveforms

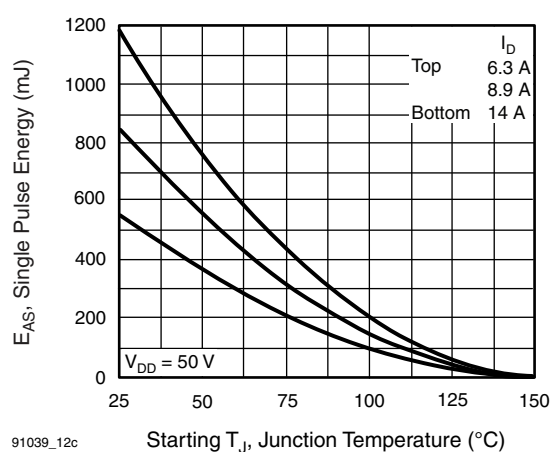


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

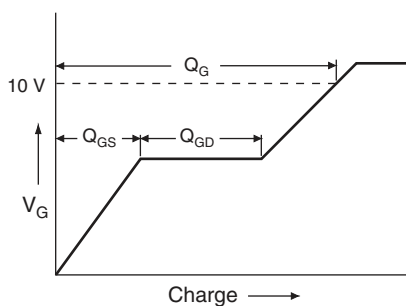


Fig. 13a - Basic Gate Charge Waveform

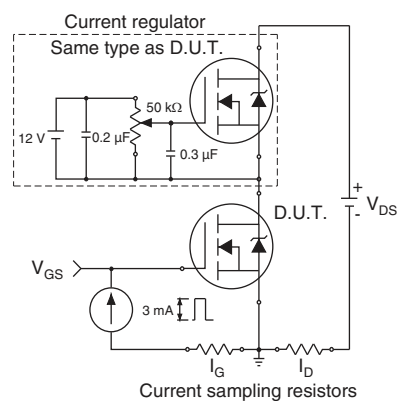
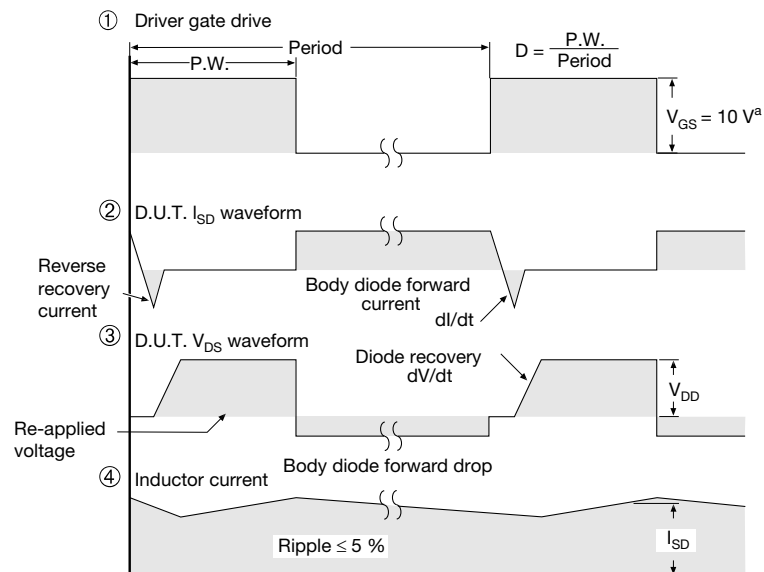
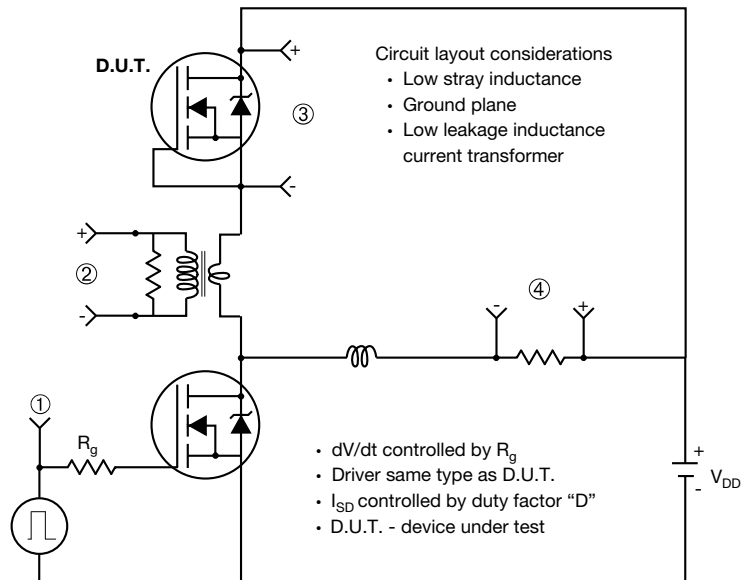


Fig. 13b - Gate Charge Test Circuit

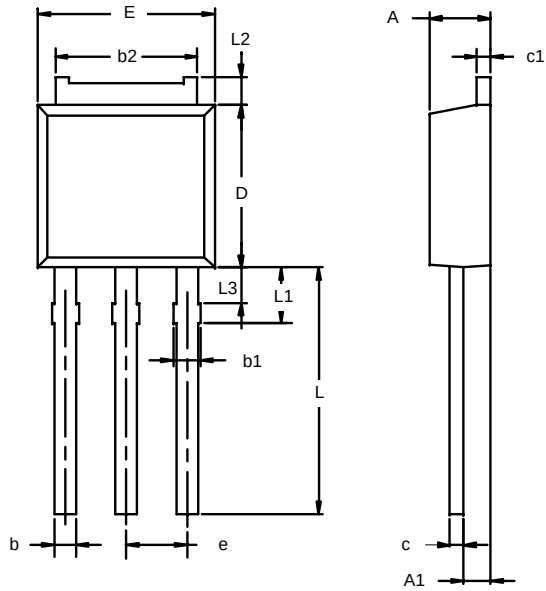
Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

TO-251AA (DPAK)

Note: Dimension L3 is for reference only.

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
e	2.28 BSC		0.090 BSC	
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060

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